

EMRA53F1H-12.000M

[Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 8, 2019)


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ITEM DESCRIPTION

MEMS Clock Oscillators LVCMOS (CMOS) 3.3Vdc 4 Pad 1.6mm x 2.0mm Plastic Surface Mount (SMD) 12.000MHz \pm 50ppm over -20°C to +70°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	12.000MHz
Frequency Tolerance/Stability	\pm 50ppm Maximum over -20°C to +70°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, and Output Load Change)
Aging at 25°C	\pm 1.5ppm Maximum First Year
Supply Voltage	3.3Vdc \pm 10%
Input Current	5mA Maximum (No Load)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -4mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL = +4mA)
Rise/Fall Time	1.2nSec Typical, 3nSec Maximum (Measured from 20% to 80% of waveform)
Duty Cycle	50 \pm 10(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Tri-State (Disabled Output: High Impedance)
Output Control Input Voltage Logic High (Vih)	70% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	30% of Vdd Maximum to Disable Output
Tri-State Output Enable Time	150nSec Maximum
Tri-State Output Disable Time	150nSec Maximum
Period Jitter (RMS)	2pSec Typical, 4pSec Maximum
RMS Phase Jitter (Fj = 900kHz to 7.5MHz; Random)	0.5pSec Typical, 1pSec Maximum
RMS Phase Jitter (Fj = 12kHz to 20MHz; Random)	1.5pSec Typical, 3pSec Maximum
Start Up Time	5mSec Maximum
Storage Temperature Range	-65°C to +150°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	JESD22-A114, HBM, 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition E, 10,000G
Moisture Sensitivity	J-STD-020, MSL 1
Solderability	MIL-STD-883, Method 2003 (Four I/O Pads on bottom of package only)
Temperature Cycling	JESD22-A104, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

EMRA53F1H-12.000M [Click part number to visit Part Number Details page](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State (High Impedance)
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	Ecliptek Manufacturing Identifier
2	Ecliptek Manufacturing Identifier (continued)

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ± 0.1

EMRA53F1H-12.000M [Click part number to visit Part Number Details page](#)

OUTPUT WAVEFORM & TIMING DIAGRAM



EMRA53F1H-12.000M [Click part number to visit Part Number Details page](#)

Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value CL includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

EMRA53F1H-12.000M [Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_s MAX to T_L (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (T_s MIN)	150°C
- Temperature Typical (T_s TYP)	175°C
- Temperature Maximum (T_s MAX)	200°C
- Time (t_s MIN)	60 - 180 Seconds
Ramp-up Rate (T_L to T_P)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds
Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T_P Target)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperature shown are applied to body of device.

EMRA53F1H-12.000M [Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	240°C Maximum
Target Peak Temperature (TP Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperature shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)